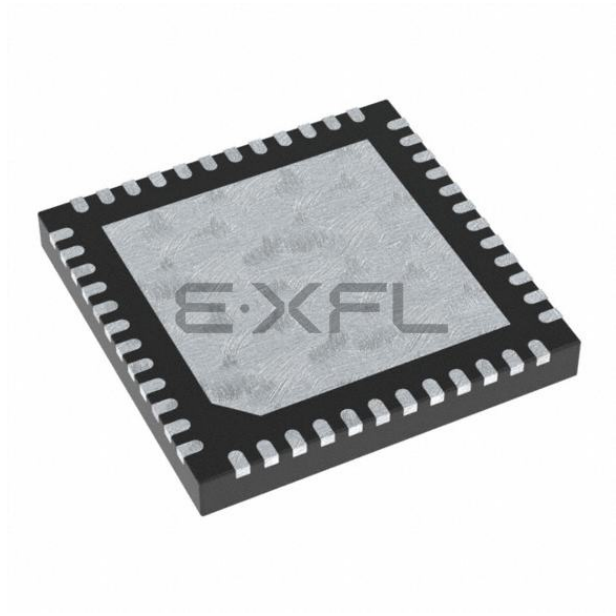

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	60MHz
Connectivity	I²C, IrDA, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	28
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3b1256-z1ut

3. Configuration Summary

The table below lists all AT32UC3B memory and package configurations:

Table 3-1. Configuration Summary

Feature	AT32UC3B0512	AT32UC3B0256/128/64	AT32UC3B1512	AT32UC3B1256/128/64
Flash	512 KB	256/128/64 KB	512 KB	256/128/64 KB
SRAM	96KB	32/32/16KB	96KB	32/16/16KB
GPIO	44		28	
External Interrupts	8		6	
TWI	1			
USART	3			
Peripheral DMA Channels	7			
SPI	1			
Full Speed USB	Mini-Host + Device		Device	
SSC	1		0	
Audio Bitstream DAC	1	0	1	0
Timer/Counter Channels	3			
PWM Channels	7			
Watchdog Timer	1			
Real-Time Clock Timer	1			
Power Manager	1			
Oscillators	PLL 80-240 MHz (PLL0/PLL1) Crystal Oscillators 0.4-20 MHz (OSC0) Crystal Oscillator 32 KHz (OSC32K) RC Oscillator 115 kHz (RCSYS)			
	Crystal Oscillators 0.4-20 MHz (OSC1)			
10-bit ADC number of channels	8		6	
JTAG	1			
Max Frequency	60 MHz			
Package	TQFP64, QFN64		TQFP48, QFN48	

4. Package and Pinout

4.1 Package

The device pins are multiplexed with peripheral functions as described in the Peripheral Multiplexing on I/O Line section.

Figure 4-1. TQFP64 / QFN64 Pinout

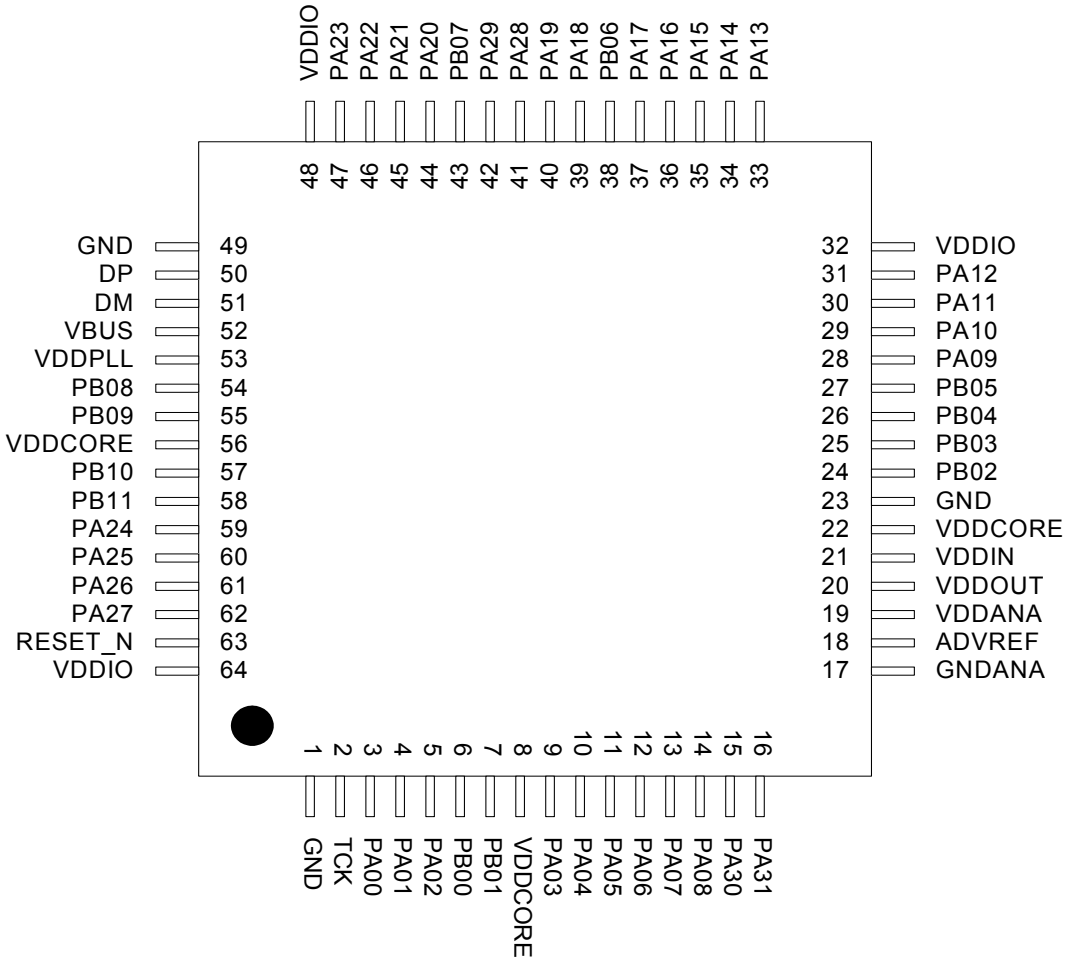
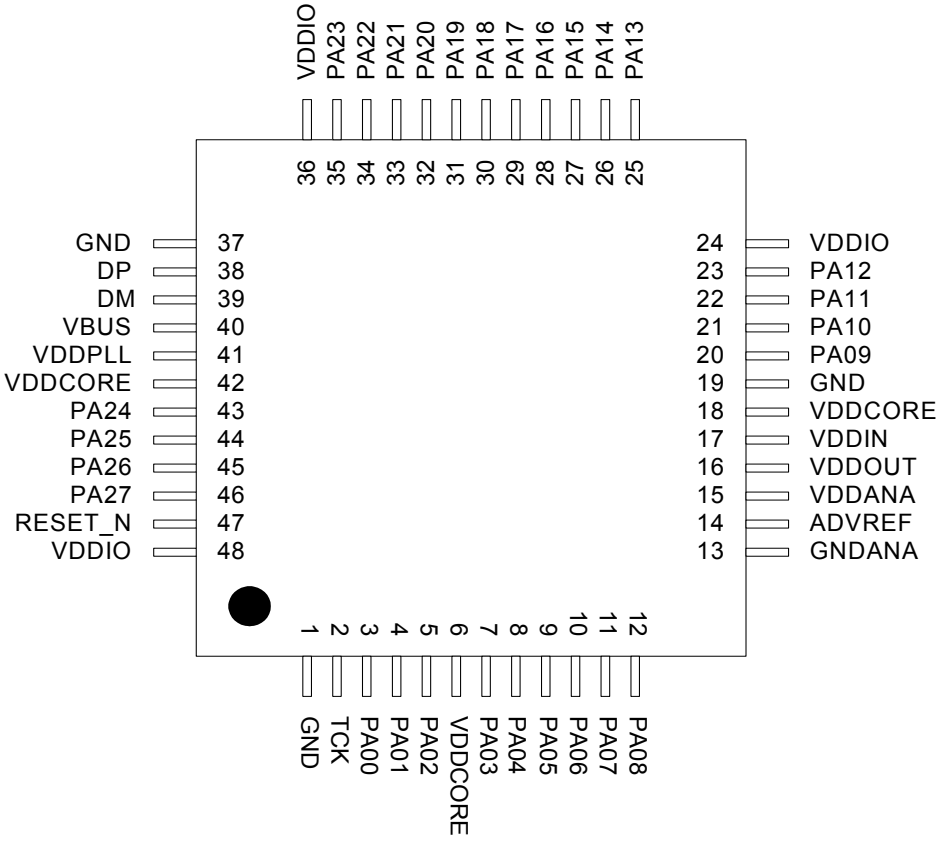


Figure 4-2. TQFP48 / QFN48 Pinout



Note: The exposed pad is not connected to anything internally, but should be soldered to ground to increase board level reliability.

4.2 Peripheral Multiplexing on I/O lines

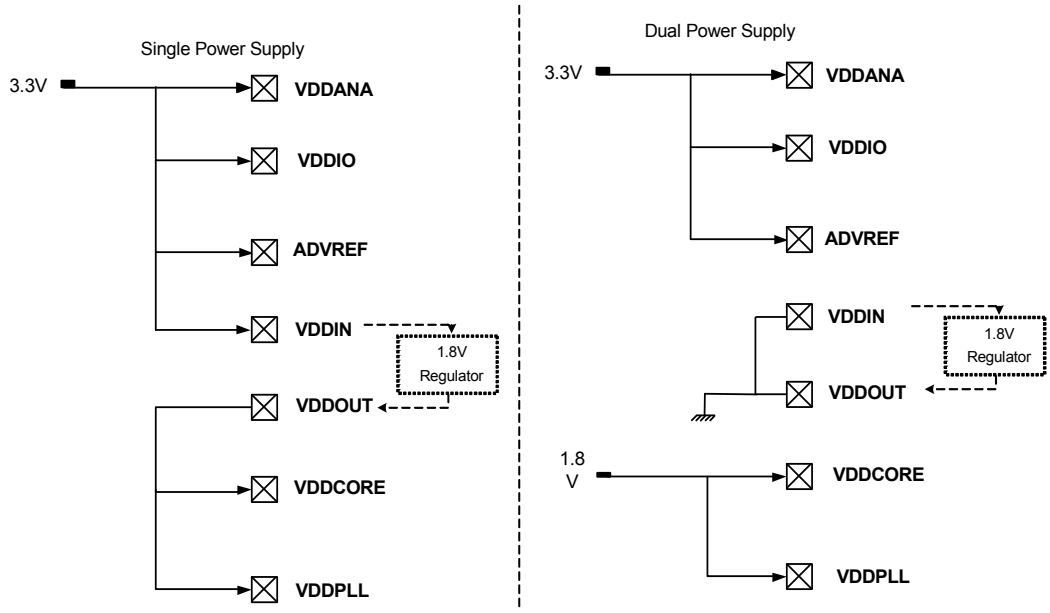
4.2.1 Multiplexed signals

Each GPIO line can be assigned to one of 4 peripheral functions; A, B, C or D (D is only available for UC3Bx512 parts). The following table define how the I/O lines on the peripherals A, B,C or D are multiplexed by the GPIO.

Table 4-1. GPIO Controller Function Multiplexing

48-pin	64-pin	PIN	GPIO Pin	Function A	Function B	Function C	Function D (only for UC3Bx512)
3	3	PA00	GPIO 0				
4	4	PA01	GPIO 1				
5	5	PA02	GPIO 2				
7	9	PA03	GPIO 3	ADC - AD[0]	PM - GCLK[0]	USBB - USB_ID	ABDAC - DATA[0]
8	10	PA04	GPIO 4	ADC - AD[1]	PM - GCLK[1]	USBB - USB_VBOF	ABDAC - DATAN[0]
9	11	PA05	GPIO 5	EIC - EXTINT[0]	ADC - AD[2]	USART1 - DCD	ABDAC - DATA[1]

Figure 5-1. Power Supply



5.6.2 Voltage Regulator

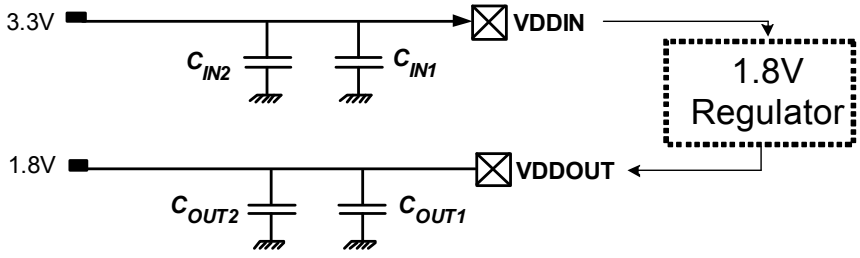
5.6.2.1 Single Power Supply

The AT32UC3B embeds a voltage regulator that converts from 3.3V to 1.8V. The regulator takes its input voltage from VDDIN, and supplies the output voltage on VDDOUT that should be externally connected to the 1.8V domains.

Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. Two input decoupling capacitors must be placed close to the chip.

Adequate output supply decoupling is mandatory for VDDOUT to reduce ripple and avoid oscillations. The best way to achieve this is to use two capacitors in parallel between VDDOUT and GND as close to the chip as possible

Figure 5-2. Supply Decoupling



6. Processor and Architecture

Rev: 1.0.0.0

This chapter gives an overview of the AVR32UC CPU. AVR32UC is an implementation of the AVR32 architecture. A summary of the programming model, instruction set, and MPU is presented. For further details, see the *AVR32 Architecture Manual* and the *AVR32UC Technical Reference Manual*.

6.1 Features

- **32-bit load/store AVR32A RISC architecture**
  - **15 general-purpose 32-bit registers**
  - **32-bit Stack Pointer, Program Counter and Link Register reside in register file**
  - **Fully orthogonal instruction set**
  - **Privileged and unprivileged modes enabling efficient and secure Operating Systems**
  - **Innovative instruction set together with variable instruction length ensuring industry leading code density**
  - **DSP extention with saturating arithmetic, and a wide variety of multiply instructions**
- **3-stage pipeline allows one instruction per clock cycle for most instructions**
  - **Byte, halfword, word and double word memory access**
  - **Multiple interrupt priority levels**
- **MPU allows for operating systems with memory protection**

6.2 AVR32 Architecture

AVR32 is a high-performance 32-bit RISC microprocessor architecture, designed for cost-sensitive embedded applications, with particular emphasis on low power consumption and high code density. In addition, the instruction set architecture has been tuned to allow a variety of microarchitectures, enabling the AVR32 to be implemented as low-, mid-, or high-performance processors. AVR32 extends the AVR family into the world of 32- and 64-bit applications.

Through a quantitative approach, a large set of industry recognized benchmarks has been compiled and analyzed to achieve the best code density in its class. In addition to lowering the memory requirements, a compact code size also contributes to the core's low power characteristics. The processor supports byte and halfword data types without penalty in code size and performance.

Memory load and store operations are provided for byte, halfword, word, and double word data with automatic sign- or zero extension of halfword and byte data. The C-compiler is closely linked to the architecture and is able to exploit code optimization features, both for size and speed.

In order to reduce code size to a minimum, some instructions have multiple addressing modes. As an example, instructions with immediates often have a compact format with a smaller immediate, and an extended format with a larger immediate. In this way, the compiler is able to use the format giving the smallest code size.

Another feature of the instruction set is that frequently used instructions, like add, have a compact format with two operands as well as an extended format with three operands. The larger format increases performance, allowing an addition and a data move in the same instruction in a single cycle. Load and store instructions have several different formats in order to reduce code size and speed up execution.

The user must also make sure that the system stack is large enough so that any event is able to push the required registers to stack. If the system stack is full, and an event occurs, the system will enter an UNDEFINED state.

6.5.2 Exceptions and Interrupt Requests

When an event other than *scall* or debug request is received by the core, the following actions are performed atomically:

1. The pending event will not be accepted if it is masked. The I3M, I2M, I1M, I0M, EM, and GM bits in the Status Register are used to mask different events. Not all events can be masked. A few critical events (NMI, Unrecoverable Exception, TLB Multiple Hit, and Bus Error) can not be masked. When an event is accepted, hardware automatically sets the mask bits corresponding to all sources with equal or lower priority. This inhibits acceptance of other events of the same or lower priority, except for the critical events listed above. Software may choose to clear some or all of these bits after saving the necessary state if other priority schemes are desired. It is the event source's responsability to ensure that their events are left pending until accepted by the CPU.
2. When a request is accepted, the Status Register and Program Counter of the current context is stored to the system stack. If the event is an INT0, INT1, INT2, or INT3, registers R8-R12 and LR are also automatically stored to stack. Storing the Status Register ensures that the core is returned to the previous execution mode when the current event handling is completed. When exceptions occur, both the EM and GM bits are set, and the application may manually enable nested exceptions if desired by clearing the appropriate bit. Each exception handler has a dedicated handler address, and this address uniquely identifies the exception source.
3. The Mode bits are set to reflect the priority of the accepted event, and the correct register file bank is selected. The address of the event handler, as shown in Table 6-4, is loaded into the Program Counter.

The execution of the event handler routine then continues from the effective address calculated.

The *rete* instruction signals the end of the event. When encountered, the Return Status Register and Return Address Register are popped from the system stack and restored to the Status Register and Program Counter. If the *rete* instruction returns from INT0, INT1, INT2, or INT3, registers R8-R12 and LR are also popped from the system stack. The restored Status Register contains information allowing the core to resume operation in the previous execution mode. This concludes the event handling.

6.5.3 Supervisor Calls

The AVR32 instruction set provides a supervisor mode call instruction. The *scall* instruction is designed so that privileged routines can be called from any context. This facilitates sharing of code between different execution modes. The *scall* mechanism is designed so that a minimal execution cycle overhead is experienced when performing supervisor routine calls from time-critical event handlers.

The *scall* instruction behaves differently depending on which mode it is called from. The behaviour is detailed in the instruction set reference. In order to allow the *scall* routine to return to the correct context, a return from supervisor call instruction, *rets*, is implemented. In the AVR32UC CPU, *scall* and *rets* uses the system stack to store the return address and the status register.

6.5.4 Debug Requests

The AVR32 architecture defines a dedicated Debug mode. When a debug request is received by the core, Debug mode is entered. Entry into Debug mode can be masked by the DM bit in the

9.2 DC Characteristics

The following characteristics are applicable to the operating temperature range: T_A = -40°C to 85°C, unless otherwise specified and are certified for a junction temperature up to T_J = 100°C.

Table 9-1. DC Characteristics

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Unit
$V_{VDDCORE}$	DC Supply Core			1.65		1.95	V
V_{VDDPLL}	DC Supply PLL			1.65		1.95	V
V_{VDDIO}	DC Supply Peripheral I/Os			3.0		3.6	V
V_{IL}	Input Low-level Voltage			-0.3		+0.8	V
V_{IH}	Input High-level Voltage	AT32UC3B064 AT32UC3B0128 AT32UC3B0256 AT32UC3B164 AT32UC3B1128 AT32UC3B1256	All I/O pins except TCK, RESET_N, PA03, PA04, PA05, PA06, PA07, PA08, PA11, PA12, PA18, PA19, PA28, PA29, PA30, PA31	2.0		5.5	V
			TCK, RESET_N, PA03, PA04, PA05, PA06, PA07, PA08, PA11, PA12, PA18, PA19, PA28, PA29, PA30, PA31	2.0		3.6	V
		AT32UC3B0512 AT32UC3B1512	All I/O pins except TCK, RESET_N, PA03, PA04, PA05, PA06, PA07, PA08, PA11, PA12, PA18, PA19, PA28, PA29, PA30, PA31	2.0		5.5	V
			TCK, RESET_N	2.5		3.6	V
			PA03, PA04, PA05, PA06, PA07, PA08, PA11, PA12, PA18, PA19, PA28, PA29, PA30, PA31	2.0		3.6	V
V_{OL}	Output Low-level Voltage	I_{OL}= -4mA for all I/O except PA20, PA21, PA22, PA23				0.4	V
		I_{OL}= -8mA for PA20, PA21, PA22, PA23				0.4	V
V_{OH}	Output High-level Voltage	I_{OL}= -4mA for all I/O except PA20, PA21, PA22, PA23		V_{VDDIO} -0.4			V
		I_{OL}= -8mA for PA20, PA21, PA22, PA23		V_{VDDIO} -0.4			V
I_{OL}	Output Low-level Current	All I/O pins except PA20, PA21, PA22, PA23				-4	mA
		PA20, PA21, PA22, PA23				-8	mA
I_{OH}	Output High-level Current	All I/O pins except for PA20, PA21, PA22, PA23				4	mA
		PA20, PA21, PA22, PA23				8	mA
I_{LEAK}	Input Leakage Current	Pullup resistors disabled				1	µA

Figure 9-1. MCU Cold Start-Up RESET_N tied to VDDIN

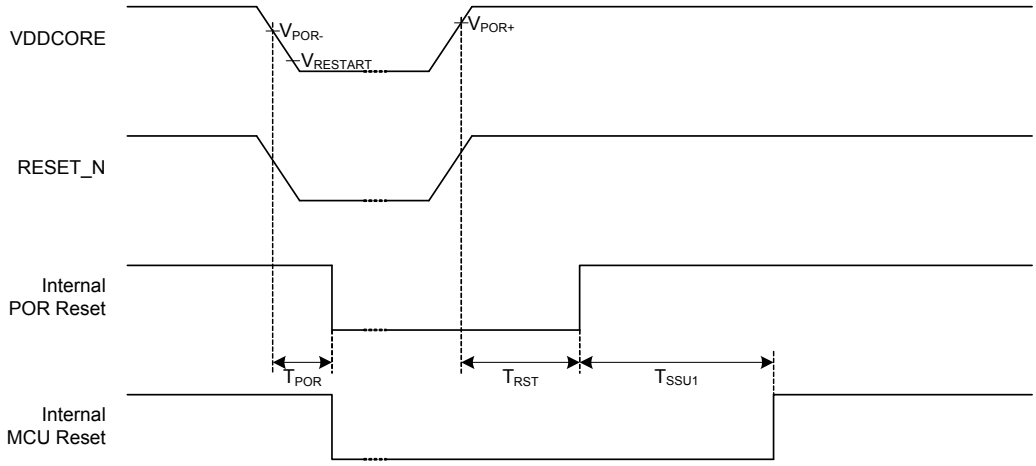


Figure 9-2. MCU Cold Start-Up RESET_N Externally Driven

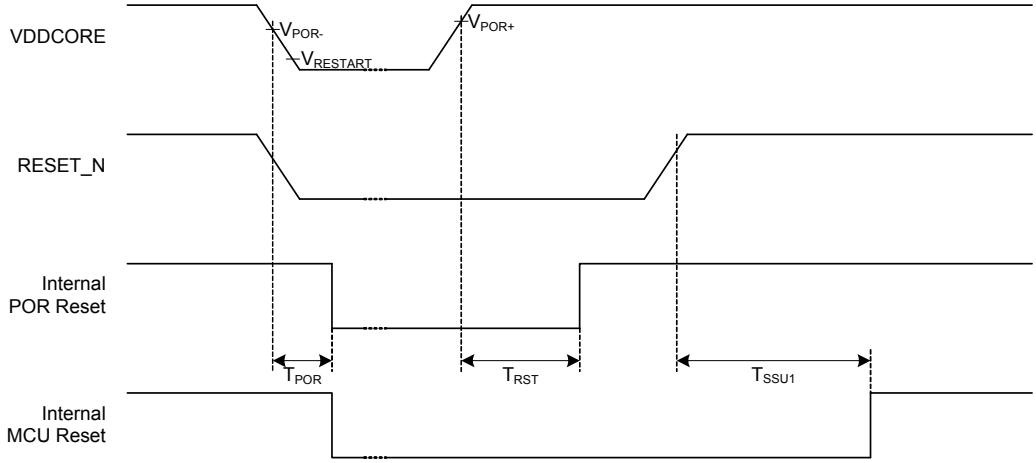
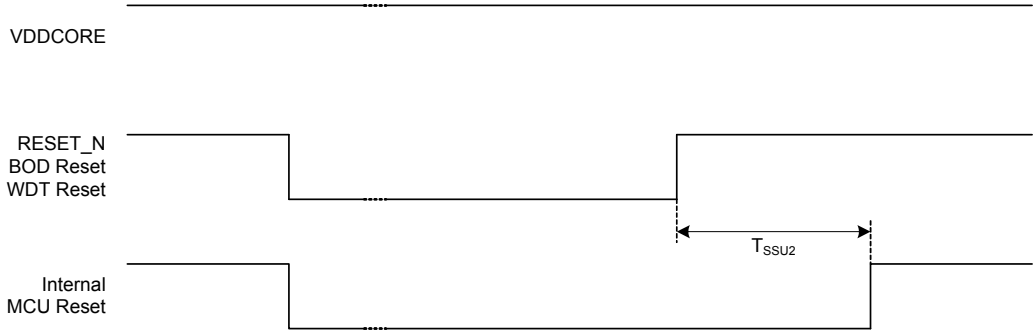


Figure 9-3. MCU Hot Start-Up



In dual supply configuration, the power up sequence must be carefully managed to ensure a safe startup of the device in all conditions.

The power up sequence must ensure that the internal logic is safely powered when the internal reset (Power On Reset) is released and that the internal Flash logic is safely powered when the CPU fetch the first instructions.

10. Mechanical Characteristics

10.1 Thermal Considerations

10.1.1 Thermal Data

Table 10-1 summarizes the thermal resistance data depending on the package.

Table 10-1. Thermal Resistance Data

Symbol	Parameter	Condition	Package	Typ	Unit
θ_{JA}	Junction-to-ambient thermal resistance	Still Air	TQFP64	49.6	°C/W
θ_{JC}	Junction-to-case thermal resistance		TQFP64	13.5	
θ_{JA}	Junction-to-ambient thermal resistance	Still Air	TQFP48	51.1	°C/W
θ_{JC}	Junction-to-case thermal resistance		TQFP48	13.7	

10.1.2 Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

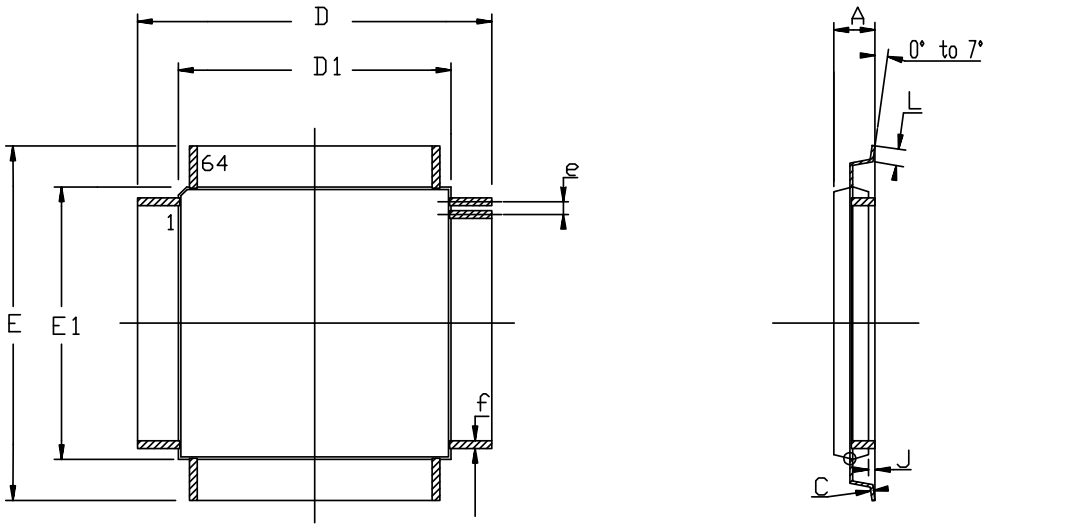
where:

- θ_{JA} = package thermal resistance, Junction-to-ambient (°C/W), provided in Table 10-1 on page 55.
- θ_{JC} = package thermal resistance, Junction-to-case thermal resistance (°C/W), provided in Table 10-1 on page 55.
- $\theta_{HEAT\ SINK}$ = cooling device thermal resistance (°C/W), provided in the device datasheet.
- P_D = device power consumption (W) estimated from data provided in the section "Power Consumption" on page 42.
- T_A = ambient temperature (°C).

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

10.2 Package Drawings

Figure 10-1. TQFP-64 package drawing



COMMON DIMENSIONS IN MM

SYMBOL	Min	Max	NOTES
A	----	1.20	
A1	0.95	1.05	
C	0.09	0.20	
D	12.00 BSC		
D1	10.00 BSC		
E	12.00 BSC		
E1	10.00 BSC		
J	0.05	0.15	
L	0.45	0.75	
e	0.50 BSC		
f	0.17	0.27	

Table 10-2. Device and Package Maximum Weight

Weight	300 mg

Table 10-3. Package Characteristics

Moisture Sensitivity Level	Jedec J-STD-20D-MSL3

Table 10-4. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	e3

10.3 Soldering Profile

Table 10-14 gives the recommended soldering profile from J-STD-20.

Table 10-14. Soldering Profile

Profile Feature	Green Package
Average Ramp-up Rate (217°C to Peak)	3°C/s
Preheat Temperature 175°C ±25°C	Min. 150°C, Max. 200°C
Temperature Maintained Above 217°C	60-150s
Time within 5·C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s
Time 25·C to Peak Temperature	Max. 8mn

Note: It is recommended to apply a soldering temperature higher than 250°C.

A maximum of three reflow passes is allowed per component.

- *PDCA*

1. **Wrong PDCA behavior when using two PDCA channels with the same PID**
   Wrong PDCA behavior when using two PDCA channels with the same PID.
   Fix/Workaround
   The same PID should not be assigned to more than one channel.

2. **Transfer error will stall a transmit peripheral handshake interface**
   If a transfer error is encountered on a channel transmitting to a peripheral, the peripheral handshake of the active channel will stall and the PDCA will not do any more transfers on the affected peripheral handshake interface.
   Fix/Workaround
   Disable and then enable the peripheral after the transfer error.

3. **TWI**

4. **The TWI RXRDY flag in SR register is not reset when a software reset is performed**
   The TWI RXRDY flag in SR register is not reset when a software reset is performed.
   Fix/Workaround
   After a Software Reset, the register TWI RHR must be read.

5. **TWI in master mode will continue to read data**
   TWI in master mode will continue to read data on the line even if the shift register and the RHR register are full. This will generate an overrun error.
   Fix/Workaround
   To prevent this, read the RHR register as soon as a new RX data is ready.

6. **TWI slave behaves improperly if master acknowledges the last transmitted data byte before a STOP condition**
   In I2C slave transmitter mode, if the master acknowledges the last data byte before a STOP condition (what the master is not supposed to do), the following TWI slave receiver mode frame may contain an inappropriate clock stretch. This clock stretch can only be stopped by resetting the TWI.
   Fix/Workaround
   If the TWI is used as a slave transmitter with a master that acknowledges the last data byte before a STOP condition, it is necessary to reset the TWI before entering slave receiver mode.

7. **TC**

8. **Channel chaining skips first pulse for upper channel**
   When chaining two channels using the Block Mode Register, the first pulse of the clock between the channels is skipped.
   Fix/Workaround
   Configure the lower channel with RA = 0x1 and RC = 0x2 to produce a dummy clock cycle for the upper channel. After the dummy cycle has been generated, indicated by the SR.CPCS bit, reconfigure the RA and RC registers for the lower channel with the real values.

- *DSP Operations*

1. **Hardware breakpoints may corrupt MAC results**
   Hardware breakpoints on MAC instructions may corrupt the destination register of the MAC instruction.
   Fix/Workaround
   Place breakpoints on earlier or later instructions.

12.2.3 Rev. F

- *PWM*

1. **PWM channel interrupt enabling triggers an interrupt**
   When enabling a PWM channel that is configured with center aligned period (CALG=1), an interrupt is signalled.
   Fix/Workaround
   When using center aligned mode, enable the channel and read the status before channel interrupt is enabled.

2. **PWN counter restarts at 0x0001**
   The PWM counter restarts at 0x0001 and not 0x0000 as specified. Because of this the first PWM period has one more clock cycle.
   Fix/Workaround
   - The first period is 0x0000, 0x0001, ..., period.
   - Consecutive periods are 0x0001, 0x0002, ..., period.

3. **PWM update period to a 0 value does not work**
   It is impossible to update a period equal to 0 by the using the PWM update register (PWM_CUPD).
   Fix/Workaround
   Do not update the PWM_CUPD register with a value equal to 0.

4. **SPI**

5. **SPI Slave / PDCA transfer: no TX UNDERRUN flag**
   There is no TX UNDERRUN flag available, therefore in SPI slave mode, there is no way to be informed of a character lost in transmission.
   Fix/Workaround
   For PDCA transfer: none.

6. **SPI bad serial clock generation on 2nd chip_select when SCBR=1, CPOL=1, and NCPHA=0**
   When multiple chip selects (CS) are in use, if one of the baudrates equal 1 while one (CSRn.SCBR=1) of the others do not equal 1, and CSRn.CPOL=1 and CSRn.NCPHA=0, then an additional pulse will be generated on SCK.
   Fix/Workaround
   When multiple CS are in use, if one of the baudrates equals 1, the others must also equal 1 if CSRn.CPOL=1 and CSRn.NCPHA=0.

7. **SPI Glitch on RXREADY flag in slave mode when enabling the SPI or during the first transfer**
   In slave mode, the SPI can generate a false RXREADY signal during enabling of the SPI or during the first transfer.
   Fix/Workaround
   1. Set slave mode, set required CPOL/CPHA.
   2. Enable SPI.
   3. Set the polarity CPOL of the line in the opposite value of the required one.
   4. Set the polarity CPOL to the required one.
   5. Read the RXHOLDING register.
   Transfers can now begin and RXREADY will now behave as expected.

8. **SPI disable does not work in SLAVE mode**
   SPI disable does not work in SLAVE mode.
   Fix/Workaround
   Read the last received data, then perform a software reset by writing a one to the Software Reset bit in the Control Register (CR.SWRST).

9. **SPI data transfer hangs with CSR0.CSAAT==1 and MR.MODFDIS==0**
   When CSR0.CSAAT==1 and mode fault detection is enabled (MR.MODFDIS==0), the SPI module will not start a data transfer.
   Fix/Workaround
   Disable mode fault detection by writing a one to MR.MODFDIS.

10. **Disabling SPI has no effect on the SR.TDRE bit**
    Disabling SPI has no effect on the SR.TDRE bit whereas the write data command is filtered when SPI is disabled. Writing to TDR when SPI is disabled will not clear SR.TDRE. If SPI is disabled during a PDCA transfer, the PDCA will continue to write data to TDR until its buffer is empty, and this data will be lost.
    Fix/Workaround
    Disable the PDCA, add two NOPs, and disable the SPI. To continue the transfer, enable the SPI and PDCA.

11. **Power Manager**

12. **If the BOD level is higher than VDDCORE, the part is constantly reset**
    If the BOD level is set to a value higher than VDDCORE and enabled by fuses, the part will be in constant reset.
    Fix/Workaround
    Apply an external voltage on VDDCORE that is higher than the BOD level and is lower than VDDCORE max and disable the BOD.

3. **When the main clock is RCSYS, TIMER_CLOCK5 is equal to PBA clock**
   When the main clock is generated from RCSYS, TIMER_CLOCK5 is equal to PBA Clock and not PBA Clock / 128.
   Fix/Workaround
   None.

13. **Clock sources will not be stopped in STATIC sleep mode if the difference between CPU and PBx division factor is too high**
    If the division factor between the CPU/HSB and PBx frequencies is more than 4 when going to a sleep mode where the system RC oscillator is turned off, then high speed clock sources will not be turned off. This will result in a significantly higher power consumption during the sleep mode.
    Fix/Workaround
    Before going to sleep modes where the system RC oscillator is stopped, make sure that the factor between the CPU/HSB and PBx frequencies is less than or equal to 4.

14. **Increased Power Consumption in VDDIO in sleep modes**
    If the OSC0 is enabled in crystal mode when entering a sleep mode where the OSC0 is disabled, this will lead to an increased power consumption in VDDIO.
    Fix/Workaround
    Disable the OSC0 through the System Control Interface (SCIF) before going to any sleep mode where the OSC0 is disabled, or pull down or up XIN0 and XOUT0 with 1 Mohm resistor.

2. **Transfer error will stall a transmit peripheral handshake interface**
   If a transfer error is encountered on a channel transmitting to a peripheral, the peripheral handshake of the active channel will stall and the PDCA will not do any more transfers on the affected peripheral handshake interface.
   Fix/Workaround
   Disable and then enable the peripheral after the transfer error.

3. **TWI**

4. **The TWI RXRDY flag in SR register is not reset when a software reset is performed**
   The TWI RXRDY flag in SR register is not reset when a software reset is performed.
   Fix/Workaround
   After a Software Reset, the register TWI RHR must be read.

5. **TWI in master mode will continue to read data**
   TWI in master mode will continue to read data on the line even if the shift register and the RHR register are full. This will generate an overrun error.
   Fix/Workaround
   To prevent this, read the RHR register as soon as a new RX data is ready.

6. **TWI slave behaves improperly if master acknowledges the last transmitted data byte before a STOP condition**
   In I2C slave transmitter mode, if the master acknowledges the last data byte before a STOP condition (what the master is not supposed to do), the following TWI slave receiver mode frame may contain an inappropriate clock stretch. This clock stretch can only be stopped by resetting the TWI.
   Fix/Workaround
   If the TWI is used as a slave transmitter with a master that acknowledges the last data byte before a STOP condition, it is necessary to reset the TWI before entering slave receiver mode.

7. **GPIO**

8. **PA29 (TWI SDA) and PA30 (TWI SCL) GPIO VIH (input high voltage) is 3.6V max instead of 5V tolerant**
   The following GPIOs are not 5V tolerant: PA29 and PA30.
   Fix/Workaround
   None.

9. **Some GPIO VIH (input high voltage) are 3.6V max instead of 5V tolerant**
   Only 11 GPIOs remain 5V tolerant (VIHmax=5V):PB01, PB02, PB03, PB10, PB19, PB20, PB21, PB22, PB23, PB27, PB28.
   Fix/Workaround
   None.

10. **TC**

11. **Channel chaining skips first pulse for upper channel**
    When chaining two channels using the Block Mode Register, the first pulse of the clock between the channels is skipped.
    Fix/Workaround
    Configure the lower channel with RA = 0x1 and RC = 0x2 to produce a dummy clock cycle for the upper channel. After the dummy cycle has been generated, indicated by the

7. **ISO7816 Mode T1: RX impossible after any TX**
   RX impossible after any TX.
   Fix/Workaround
   SOFT_RESET on RX+ Config US_MR + Config_US_CR.

8. **The RTS output does not function correctly in hardware handshaking mode**
   The RTS signal is not generated properly when the USART receives data in hardware handshaking mode. When the Peripheral DMA receive buffer becomes full, the RTS output should go high, but it will stay low.
   Fix/Workaround
   Do not use the hardware handshaking mode of the USART. If it is necessary to drive the RTS output high when the Peripheral DMA receive buffer becomes full, use the normal mode of the USART. Configure the Peripheral DMA Controller to signal an interrupt when the receive buffer is full. In the interrupt handler code, write a one to the RTSDIS bit in the USART Control Register (CR). This will drive the RTS output high. After the next DMA transfer is started and a receive buffer is available, write a one to the RTSEN bit in the USART CR so that RTS will be driven low.

9. **Corruption after receiving too many bits in SPI slave mode**
   If the USART is in SPI slave mode and receives too much data bits (ex: 9bitsinstead of 8 bits) by the SPI master, an error occurs. After that, the next reception may be corrupted even if the frame is correct and the USART has been disabled, reset by a soft reset and re-enabled.
   Fix/Workaround
   None.

10. **USART slave synchronous mode external clock must be at least 9 times lower in frequency than CLK_USART**
    When the USART is operating in slave synchronous mode with an external clock, the frequency of the signal provided on CLK must be at least 9 times lower than CLK_USART.
    Fix/Workaround
    When the USART is operating in slave synchronous mode with an external clock, provide a signal on CLK that has a frequency at least 9 times lower than CLK_USART.

11. **HMATRIX**

12. **In the PRAS and PRBS registers, the MxPR fields are only two bits**
    In the PRAS and PRBS registers, the MxPR fields are only two bits wide, instead of four bits. The unused bits are undefined when reading the registers.
    Fix/Workaround
    Mask undefined bits when reading PRAS and PRBS.

- *FLASHC*

1. **Reading from on-chip flash may fail after a flash fuse write operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands).**
   After a flash fuse write operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands), the following flash read access may return corrupted data. This erratum does not affect write operations to regular flash memory.
   Fix/Workaround
   The flash fuse write operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands) must be issued from internal RAM. After the write operation, perform a dummy flash page write operation (FLASHC WP). Content and location of this page is not important

13.6 Rev. G – 06/2009

1. Open Drain Mode removed from GPIO section.
2. Updated Errata section.

13.7 Rev. F – 04/2008

1. Updated Errata section.

13.8 Rev. E – 12/2007

1. Updated Memory Protection section.

13.9 Rev. D – 11/2007

1. Updated Processor Architecture section.
2. Updated Electrical Characteristics section.

13.10 Rev. C – 10/2007

1. Updated Features sections.
2. Updated block diagram with local bus figure
3. Add schematic for HMatrix master/slave connection.
4. Updated Features sections with local bus.
5. Added SPI feature to USART section.
6. Updated USBB section.
7. Updated ADC trigger selection in ADC section.
8. Updated JTAG and Boundary Scan section with programming procedure.
9. Add description for silicon revision D

13.11 Rev. B – 07/2007

1. Updated registered trademarks
2. Updated address page.

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